

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	50	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
Average Rectified Output Current	I _O	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	100	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	38	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	28	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	0.39	—	V	I _F = 2.5A, T _J = +25°C
			0.46	0.53		I _F = 5A, T _J = +25°C
			0.32	—		I _F = 2.5A, T _J = +125°C
			0.44	0.5		I _F = 5A, T _J = +125°C
Leakage Current (Note 6)	I _R	—	30	150	μA	V _R = 50V, T _J = +25°C
		—	7	45	mA	V _R = 50V, T _J = +125°C

Notes: 5. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.56" x 0.73" copper pad.
 6. Short duration pulse test used to minimize self-heating effect.

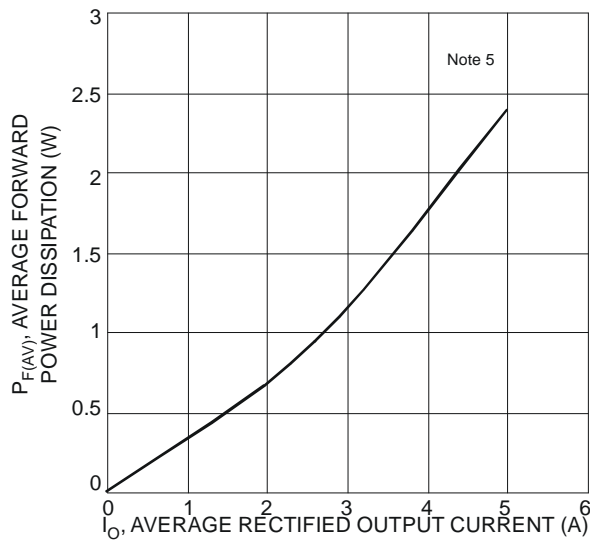


Figure 1 Forward Power Dissipation

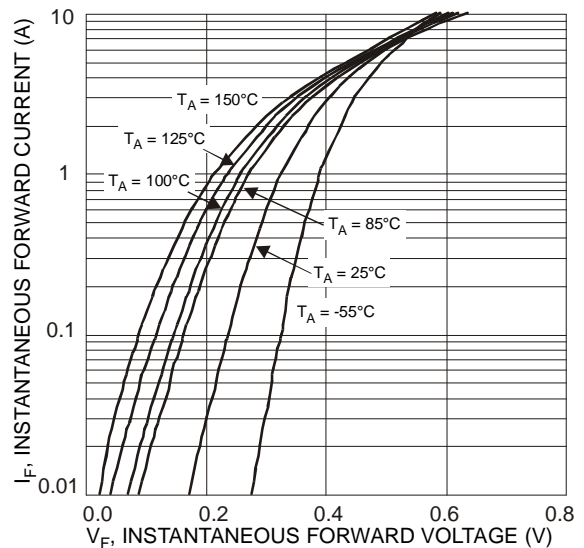
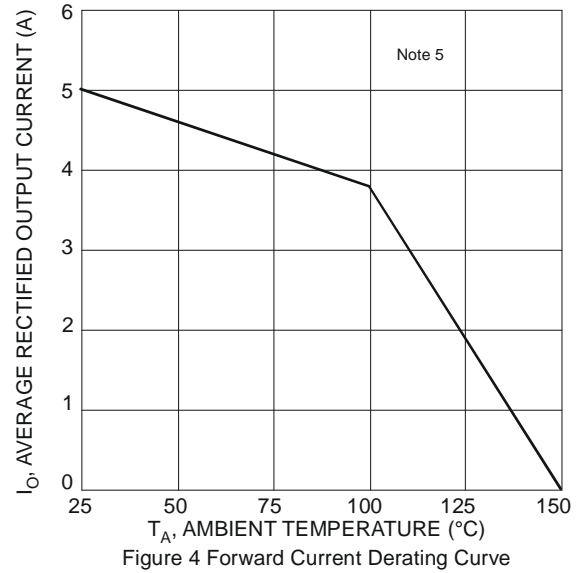
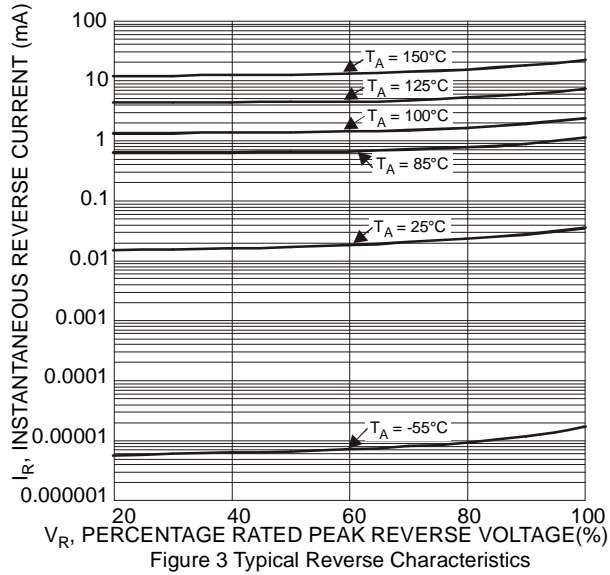
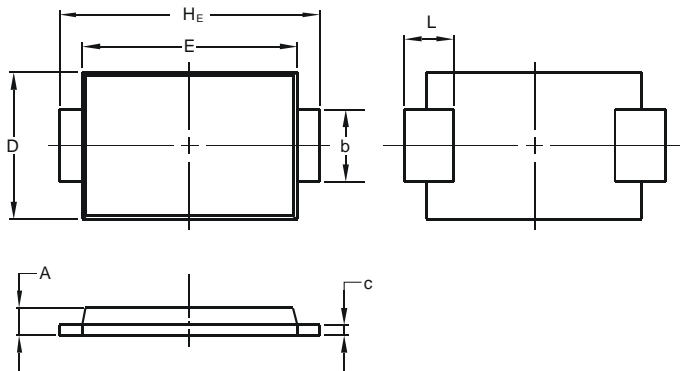


Figure 2 Typical Forward Characteristics



Package Outline Dimensions

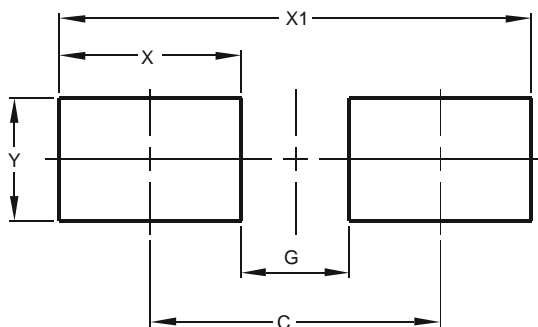
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
H _E	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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